

C2220X273M1TACTU

Aliases (C2220X273M1TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.027 uF, 20%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

0.027 uF

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

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Т	1mm +/-0.15mm	
S	3.5mm MIN	
В	0.7mm +/-0.35mm	
Packaging Specifications		

nm	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	20%
	Voltage DC	100 VDC
	Dielectric Withstanding Voltage	250 VDC
nm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
astic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	37.037 GOhms

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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